Single-Channel Transient Voltage Suppressor

Product Description

ON Semiconductor's CM6116 is an *Application Specific Integrated Passive* $^{\text{TM}}$ (ASIP $^{\text{M}}$) component in a 2 x 2, 4-bump, 0.4 mm pitch, CSP form factor. This device is designed for:

- Transient Voltage Suppression
- Electrostatic Discharge Protection
- Electrical Overstress Protection

Features

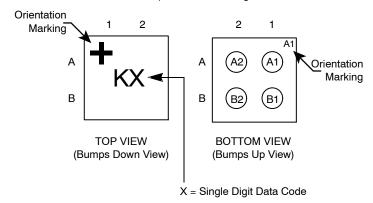
- 4-Bump, 0.80 mm X 0.80 mm Footprint Chip Scale Package (CSP)
- These Devices are Pb-Free and are RoHS Compliant

Table 1. PIN DESCRIPTIONS

| Pins | Description | |
|-----------|---------------|--|
| A1 and A2 | TVS Channel | |
| B1 and B2 | Device Ground | |

PACKAGE / PINOUT DIAGRAMS

4-Bump WLCSP4 Package





ON Semiconductor®

http://onsemi.com



WLCSP4 XX SUFFIX CASE 567CB

ELECTRICAL SCHEMATIC



MARKING DIAGRAM



K = CM6116 X = Single Digit Data Code

ORDERING INFORMATION

| Device | Package | Shipping [†] |
|--------|---------------------|-----------------------|
| CM6116 | WLCSP4 (Pb-Free) | 10,000/Tape & Reel |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

ELECTRICAL SPECIFICATIONS AND CONDITIONS

Table 2. ABSOLUTE RATINGS

| Parameter | Rating | Units |
|---|--------|-------|
| Failing to Nonconductive, I $^2 t$ (Maximum Ipp Value Using 10/1000 μs Pulse). (Notes 1 and 2) | 100 | Α |

^{1.} The device must not burn to open-circuit, when the value is below maximum $I_{\mbox{\footnotesize{PP}}}$.

Table 3. STANDARD OPERATING CONDITIONS

| Parameter | Rating | Units |
|-----------------------------|-------------|-------|
| Storage Temperature Range | –55 to +150 | °C |
| Operating Temperature Range | -30 to +85 | °C |

Table 4. ELECTRICAL OPERATING CHARACTERISTICS (Note 1)

| Symbol | Parameter | Conditions | Min | Тур | Max | Units |
|------------------|--|--|------------|---------|-----|-------|
| I _{OFF} | Stand-Off Quiescent Current | Stand-Off Voltage V _{OFF} = 10 V | | | 500 | nA |
| V _{BR} | Break Down Voltage | Break Down Current I _{BR} = 15 mA | 16 | | | V |
| V _{CL} | Clamping Voltage during Transient | Clamping Current I _{CL} = 1 A (Note 3) | | | 20 | V |
| V _F | Forward Voltage | Forward Current I _F = 850 mA | | | 1.3 | V |
| C _{L1} | Line Capacitance | V _{BIAS} = 0 V | | 190 | | pF |
| C _{L2} | | V _{BIAS} = 5 V, T _A = 25°C; | 73 | 92 | | pF |
| V _{ESD} | ESD Protection Peak Discharge Voltage at any Channel Input a) Contact Discharge per IEC 61000-4-2 Standard b) Air Discharge per IEC 61000-4-2 Standard | T _A = 25°C (Note 2) | ±30 ±30 | | | kV |
| | Minimum Attenuation Freq = 80 MHz - 1 Ghz Freq = 1 - 4 GHz | $R_{SOURCE} = R_{LOAD} = 50 \Omega$ $T_A = 25$ °C | | 8 20 | | dB |

^{1.} All parameters specified for $T_A = -30^{\circ}C$ to $85^{\circ}C$ unless otherwise noted. 2. Standard IEC 61000–4–2 with $C_{Discharge} = 150$ pF, $R_{Discharge} = 330$ Ω . 3. Transient: 8 x 20 μ s current pulse.

^{2.} This parameter is characterized at 25°C using an ON Semiconductor-specific test board.

RF CHARACTERISTICS

$T_A = 25$ °C, 50 Ω Environment

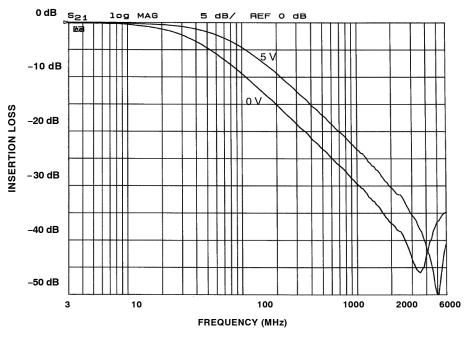


Figure 1. Insertion Loss (0 V and 5 V Bias)

MECHANICAL SPECIFICATION

Table 5. VERTICAL STRUCTURE DIMENSIONS (nominal)

| Ref. | Parameter | Material | Dimension |
|------|--|--------------|-----------|
| а | Die Thickness | Silicon | 406 μm |
| b | Bump Standoff | | 194 μm |
| | UBM-(Ti/Cu) | Plated Cu | 7 μm |
| d | | Sputtered Cu | 0.4 μm |
| | | Sputtered Ti | 0.1 μm |
| е | UBM Wetting Area Diameter | | 240 μm |
| f | Solder Bump Diameter after Bump Reflow | | 270 μm |
| С | Metal Pad Height | AlSiCu | 1.5 μm |
| g | Metal Pad Diameter | | 284 μm |
| D2 | | | 0.406 mm |
| D1 | Finished Thickness | | 0.600 mm |

Vertical Structure Specification*

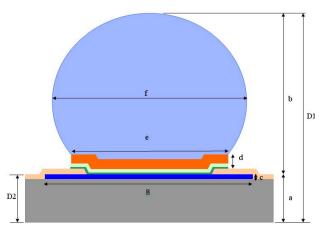
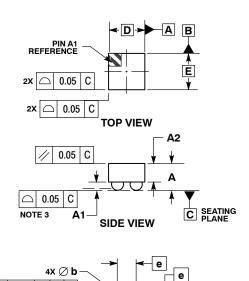


Figure 2. Sectional View

^{*} Daisy Chain CM6008

PACKAGE DIMENSIONS

WLCSP4, 0.8x0.8 CASE 567CB-01 **ISSUE O**

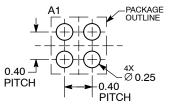


NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M. 1994.
- CONTROLLING DIMENSION: MILLIMETERS. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

| | MILLIMETERS | | | |
|-----|-------------|------|--|--|
| DIM | MIN | MAX | | |
| Α | 0.57 | 0.63 | | |
| A1 | 0.17 | 0.24 | | |
| A2 | 0.41 REF | | | |
| b | 0.24 | 0.29 | | |
| D | 0.80 BSC | | | |
| E | 0.80 BSC | | | |
| е | 0.40 BSC | | | |

RECOMMENDED **SOLDERING FOOTPRINT***



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

CAB 0.05 \oplus 0.03 С **BOTTOM VIEW**

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